

L Number	Hits	Search Text	DB	Time stamp
1	3634	324/754.ccls. or 324/758.ccls. or 324/765.ccls. and (contact same attachment same electromagnet)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 11:53
2	72	(324/754.ccls. or 324/758.ccls. or 324/765.ccls. and (contact same attachment same electromagnet)) and (apparatus adj5 probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:11
3	3	((324/754.ccls. or 324/758.ccls. or 324/765.ccls. and (contact same attachment same electromagnet)) and (apparatus adj5 probing)) and electromagnet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 12:12
4	109	324/758.ccls. and (contact with mechanism)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:16
5	0	324/354.ccls. and (contact with mechanism)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:19
6	96938	contact with mechanism	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:17
7	56	324/354.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:18
8	0	324/754.ccls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:19
9	237	324/754.ccls. and (contact with mechanism)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 14:20
-	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:18
-	53138	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:19
-	9052	(((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:21
-	1115	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:22

	267	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:24
	204	(((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))) and (substrate with (removal or removed or removing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:26
	3106	324/754.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
	747	324/758.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 13:08
	3027	324/765.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
	6438	324/754.cccls. or 324/758.cccls. or 324/765.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 11:51
	669	(automated and camera and (contact adj3 surface) and alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:04
	15	(324/754.cccls. or 324/758.cccls. or 324/765.cccls.) and ((automated and camera and (contact adj3 surface) and alignment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:57
	3048	( camera and (contact adj3 surface) and alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:05
	56	(324/754.cccls. or 324/758.cccls. or 324/765.cccls.) and (( camera and (contact adj3 surface) and alignment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:23
	286	324/758.cor.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:40
	219	324/754.cccls. and 324/758.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:57
	1	6404212.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:57